



Part Number : 781560001

Product Description : 1.00mm Pitch DDR3 DIMM Socket, Vertical, Surface Mount, with Beveled Metal Pins, Black Housing and Latches, 0.76µm Gold (Au) Plating, 3.94mm Beveled Metal Pin Length, 1.57mm PCB Thickness, 240 Circuits, Lead-Free
Status : Obsolete

Series Number : 78156
Product Category : Memory Module Connectors

Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2024)4144-DC (27 June 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Obsolete
Category	Memory Module Connectors
Series	78156
Description	1.00mm Pitch DDR3 DIMM Socket, Vertical, Surface Mount, with Beveled Metal Pins, Black Housing and Latches, 0.76µm Gold (Au) Plating, 3.94mm Beveled Metal Pin Length, 1.57mm PCB Thickness, 240 Circuits, Lead-Free
Component Type	Socket
JEDEC Outline	MO-269
Product Family	DDR3 DIMM Sockets
Product Name	DDR3 DIMM
UPC	800756674803

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage Key	Center
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Durability (mating cycles max)	25
Entry Angle	Vertical
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Black
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin

Material - Resin	High Temperature Thermoplastic
Net Weight	8.847/g
Packaging Type	Tray
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
Pitch - Mating Interface	1.00mm
Pitch - Termination Interface	1.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	40
Lead-Free Process Capability	REFLOW
Max-Cycle	2
Max-Temp	260